GND

RESET

TPS3809 ... DBV PACKAGE (TOP VIEW)

2

3

VDD

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- 3-Pin SOT-23 Package
- Supply Current of 9 μA (Typical)
- Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, 5 V
- Power-On Reset Generator With Fixed Delay Time of 200 ms
- Pin-For-Pin Compatible With MAX 809
- Temperature Range . . . –40°C to 85°C

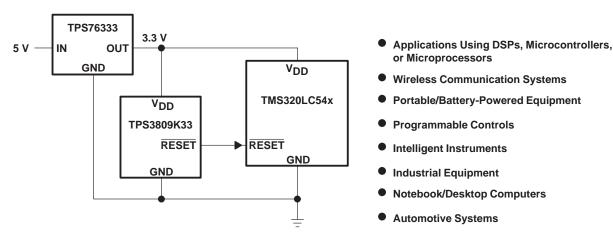
description

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, RESET is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps RESET active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)} = 200$ ms, starts after V_{DD} has risen above the threshold voltage V_{IT} . When the supply voltage drops below the threshold voltage V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of -40° C to 85° C.

typical applications





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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AVAILABLE OPTIONS									
Τ _Α	DEVICE NAME THRESHOLD VOLTAGE MARKIN								
	TPS3809J25DBVR [†]	TPS3809J25DBVT‡	2.25 V	PCZI					
–40°C to 85°C	TPS3809L30DBVR [†]	TPS3809L30DBVT [‡]	2.64 V	PDAI					
-40°C 10 85°C	TPS3809K33DBVR [†]	TPS3809K33DBVT [‡]	2.93 V	PDBI					
	TPS3809I50DBVR [†]	TPS3809I50DBVT [‡]	4.55 V	PDCI					

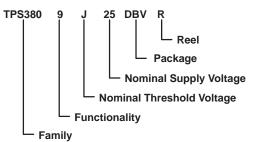
[†] The DBVR passive indicates tape and reel of 3000 parts.

[‡] The DBVT passive indicates tape and reel of 250 parts.

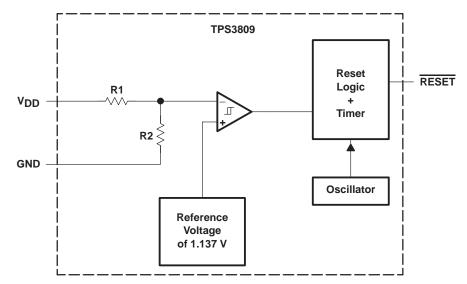
FUNCTION/TRUTH TABLE, TPS3809

V _{DD} >V _{IT}	RESET
0	L
1	н

ORDERING INFORMATION



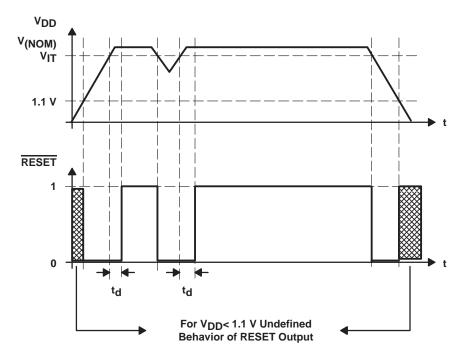
functional block diagram





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timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

· · · ·	
Supply voltage, V _{DD} (see Note1)	
All other pins (see Note 1)	
Maximum low output current, I _{OL}	
Maximum high output current, IOH	
Input clamp current, I _{IK} (VI<0 or VI>VDD)	±20 mA
Output clamp current, I _{OK} (V _O <0 or V _O >V _{DD})	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	–40°C to 85°C
Storage temperature range, T _{stg}	
Soldering temperature	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t=1000h continuously.

DISSIPATION RATING TABLE								
PACKAGE	$T_A < 25^{\circ}C$ DERATING FACTOR $T_A = 70^{\circ}C$ $T_A = 85^{\circ}C$ CKAGE POWER RATING ABOVE $T_A = 25^{\circ}C$ POWER RATING POWER RATING							
DBV	437 mW	3.5 mW/°C	280 mW	227 mW				

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V _{DD}	2	6	V
Operating free-air temperature range, T _A	-40	85	°C



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					•	•	·

	PARAMETER		TEST CO	TEST CONDITIONS			MAX	UNIT
			V _{DD} = 2.5 V to 6 V	/, I _{OH} = –500 μA	V _{DD} -0.2			
∨он	VOH High-level output voltage		V _{DD} = 3.3 V,	I _{OH} = -2 mA	V _{DD} -0.4			V
			V _{DD} = 6 V,	$I_{OH} = -4 \text{ mA}$	V _{DD} -0.4			
			$V_{DD} = 2 V \text{ to } 6 V,$	I _{OL} = 500 μA			0.2	
VOL	Low-level output voltage		V _{DD} = 3.3 V,	I _{OL} = 2 mA			0.4	V
			V _{DD} = 6 V,	$I_{OL} = 4 \text{ mA}$			0.4	
	Power-up reset voltage (see Note a	2)	$V_{DD} \ge 1.1 V$,	I _{OL} = 50 μA			0.2	V
		TPS3809J25			2.20	2.25	2.30	V
\/. _	Negative-going input threshold	TPS3809L30		2.58	2.64	2.70		
VIT-	voltage (see Note 3)	TPS3809K33	T _A - 40°C to 85°C		2.87	2.93	2.99	v
		TPS3809I50			4.45	4.55	4.65	
		TPS3809J25				30		
. V.	Hystorogia	TPS3809L30				35		mV
V _{hys}	Hysteresis	TPS3809K33				40		mv
		TPS3809I50]			60		
IDD Supply current		V _{DD} = 2 V, Outpu	ut unconnected		9	12		
		$V_{DD} = 6 V$, Output unconnected			20	25	μA	
Ci	Input capacitance		$V_{I} = 0 V \text{ to } V_{DD}$			5		pF

NOTES: 2. The lowest supply voltage at which $\overrightarrow{\text{RESET}}$ becomes active. $t_{r, VDD} \ge 15 \,\mu\text{s/V}$. 3. To ensure best stability of the threshold voltage, a bypass capacitor ($0.1 \,\mu\text{F}$ ceramic) should be placed near the supply terminals.

timing requirements at RL = 1 MΩ, CL = 50 pF, TA = 25°C

	PARAMETER		Т	MIN	TYP	MAX	UNIT	
tw	Pulse width	at V _{DD}	$V_{DD} = V_{IT-} + 0.2 V,$	$V_{DD} = V_{IT-} - 0.2 V$	3			μs

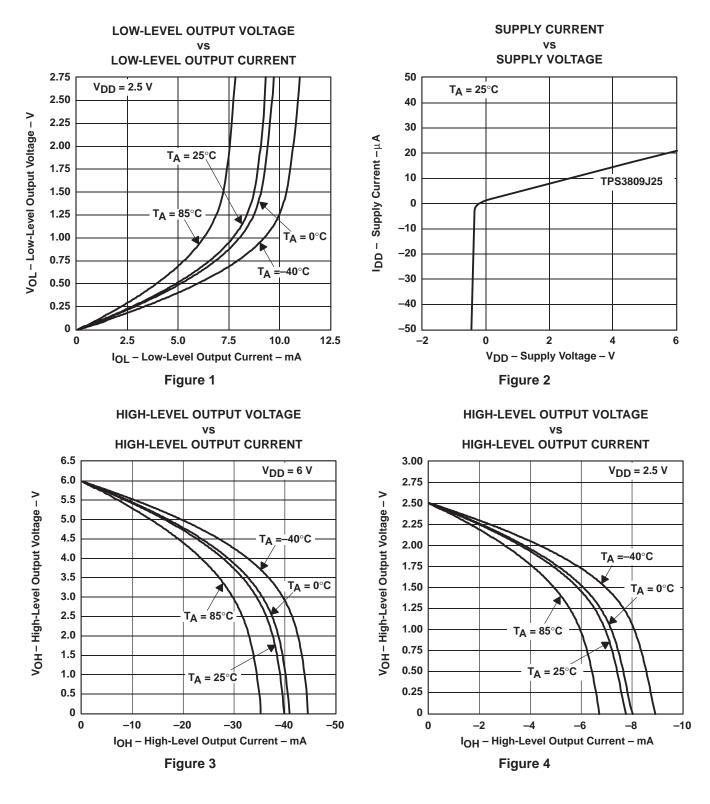
switching characteristics at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t _d	Delay time		$V_{DD} \ge V_{IT-} + 0.2 V$, See timing diagram	120	200	280	ms
^t PHL	Propagation (delay) time, high-to-low-level output	V _{DD} to RESET delay	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$		1		μs



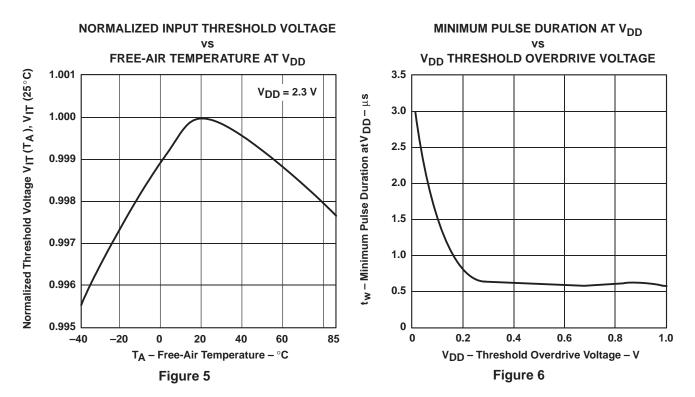
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS

18-Sep-2008

PACKAGING INFORMATION

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS3809I50DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

Addendum-Page 1 WWW.BDTIC.com/TI

PACKAGE OPTION ADDENDUM



⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS3809I50, TPS3809J25, TPS3809K33, TPS3809L30 :

Automotive: TPS3809I50-Q1, TPS3809J25-Q1, TPS3809K33-Q1, TPS3809L30-Q1
Enhanced Product: TPS3809I50-EP, TPS3809K33-EP, TPS3809L30-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

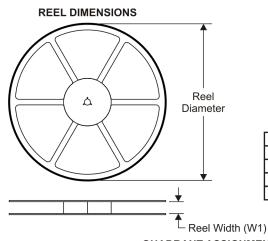
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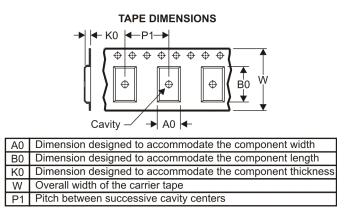
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50DBVR	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809I50DBVT	SOT-23	DBV	3	250	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVR	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVT	SOT-23	DBV	3	250	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3

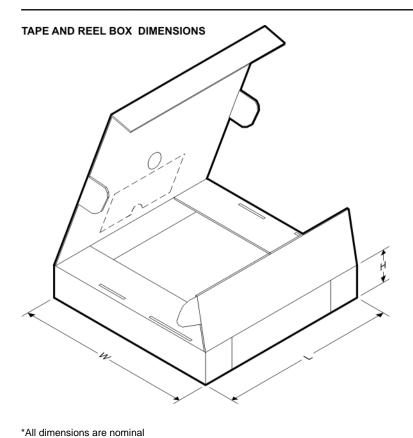
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TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Aug-2010

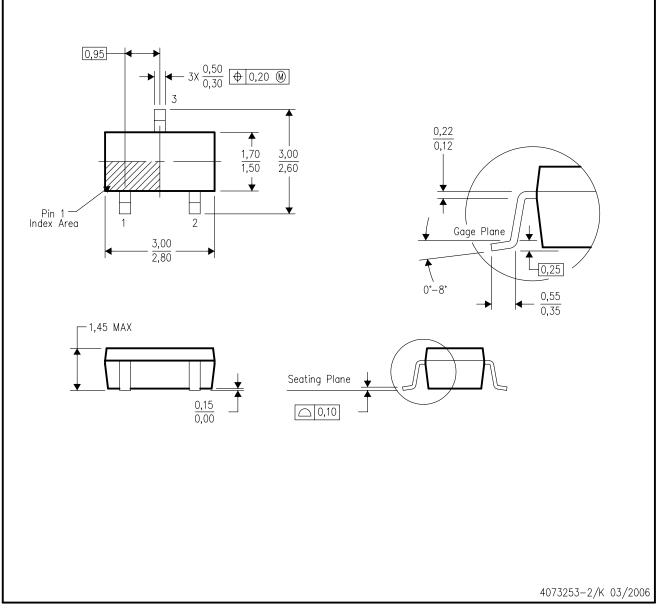


Package Drawing Device Package Type Pins SPQ Length (mm) Width (mm) Height (mm) TPS3809I50DBVR SOT-23 DBV 3 3000 182.0 182.0 20.0 TPS3809I50DBVT SOT-23 DBV 3 250 182.0 20.0 182.0 TPS3809J25DBVR SOT-23 DBV 3 3000 182.0 182.0 20.0 TPS3809J25DBVT SOT-23 DBV 182.0 3 250 182.0 20.0 TPS3809K33DBVR SOT-23 DBV 3 3000 180.0 180.0 18.0 TPS3809K33DBVT SOT-23 DBV 3 250 180.0 180.0 18.0 TPS3809L30DBVR 3 180.0 180.0 SOT-23 DBV 3000 18.0

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DBV (R-PDSO-G3)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.



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